AMENDMENTS TO THE CLAIMS

Please amend claims 1 and 9 as shown below. Please add new claims 21 and 22. This listing of claims will replace all prior versions, and listings, of claims in the application:

Complete Listing of Claims:

1. (Currently Amended) A copper foil for lamination to a dielectric substrate, comprising:

said copper foil; and

a laser ablation inhibiting layer coating said copper foil, said laser ablation inhibiting layer having an average surface roughness of between 0.4 micron and 0.7 micron wherein said average surface roughness provides said laser ablation inhibiting layer with a lamination peel strength to ~~that is effective to provide a lamination peel strength to~~ flame retardant, fiberglass reinforced, epoxy of at least 4.5 pounds per inch; and

further wherein said laser ablation inhibiting layer comprises nodules having an average height of less than 0.75 micron.

2. (Original) The copper foil of claim 1 wherein the average surface roughness is between 0.4 micron and 0.6 micron.

3. (Canceled)

4. (Original) The copper foil of claim 3 wherein said nodules have an average height of from 0.3 micron to 0.6 micron.

5. (Original) The copper foil of claim 2 wherein said laser ablation inhibiting layer is a codeposited mixture of chromium and zinc and their oxides.

6. (Original) The copper foil of claim 4 wherein said laser ablation inhibiting layer is a codeposited mixture of chromium and zinc and their oxides.

7. (Original) The copper foil of claim 2 wherein said laser ablation inhibiting layer is mixture of a metal and a metal oxide and said metal oxide is selected from the group consisting of oxides of chromium, tungsten and molybdenum.

8. (Original) The copper foil of claim 4 wherein said laser ablation inhibiting layer is mixture of a metal and a metal oxide and said metal oxide is selected from the group consisting of oxides of chromium, tungsten and molybdenum.

9. (Currently Amended) An electrically conductive circuit, comprising:

a dielectric substrate having opposing first and second sides;

a first copper foil layer laminated to a first side thereof, said copper foil layer coated with a laser ablation inhibiting layer having an average surface roughness of between 0.4 micron and 0.7 micron wherein said average surface roughness provides said laser inhibiting layer with a lamination peel strength to ~~that is effective to provide a lamination peel strength to~~ fire retardant, fiberglass reinforced, epoxy of at least 4.5 pounds per inch;

said dielectric layer having a via extending therethrough and terminating at an interface between said dielectric layer and said first copper foil layer.

10. (Original) The electrically conductive circuit of claim 9 wherein the average surface roughness of said laser ablation inhibiting layer is between 0.4 micron and 0.6 micron.

11. (Original) The electrically conductive circuit of claim 10 wherein said laser ablation inhibiting layer comprises nodules having an average height of from 0.3 micron to 0.6 micron.

12. (Original) The copper foil of claim 11 wherein said laser ablation inhibiting layer is a codeposited mixture of chromium and zinc and their oxides.

13. (Original) The copper foil of claim 11 wherein said laser ablation inhibiting layer is mixture of a metal and a metal oxide and said metal oxide is selected from the group consisting of oxides of chromium, tungsten and molybdenum.

14. (Original) The copper foil of claim 11 wherein said dielectric substrate is selected from the group consisting of glass reinforced epoxy and polyimide.

Claims 15.-20. (Canceled)